No. 7, Jalan SS16/1, 47500 Subang Jaya Selangor Darul Ehsan, Malaysia

Information Sheet

Dequested by:	FTMY	Dated: Click here to enter a date.
Requested by:	1. 1 IAI 1	Dated. Click here to enter a date.
Business Information:		
Company Name:		
Person to Contact:		
Title:		Salutation: Mr.
Office/Plant Address:		
Country:		ZIP:
Email:		TEL:
DID:		Fax:
Opportunity Information	1:	
Application:		
Market:		
Quantity: Per Year		
System Details/ Technic		
Cold Side Temp. (Tc):	$[C^{o}]$	10c
Hot Side Temp. (Th):	$[C^{o}]$	▼
Δ Temperature (Δ T): Δ T = Th - Tc	[C°]	OBJECT BEING COOLED Thermoelectric module
Heat Load (Qc): (Active + Passive)	[W]	Heat Sink Th
Ambient Temp. (Ta):	[C°]	
Humidity	[%]	Qh'
Heat Sink Thermal		To Ambient, Ta
Resistance, (θh) :	[C/W]	
(Ta – Th)/Qh		Vin & lin
Available (Vin):	[V]	Figure shows a TEC operating in cooling mode. For heating mode Tc
Power (Iin):	[A]	and Th remain in the same positions and Qc/Qh/Vin/Iin will be negative indicating that they are the opposite direction as shown.
Size Requirements:		Cooling mode defined as Tc <ta and="" as="" heating="" mode="" tc="">Ta</ta>
Width (W):	[mm]	<u> </u>
Length (L):	[mm]	W
Height (H):	[mm]	н <u>гоооооооооооооооооооооооооооооооооооо</u>
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Application Notes/ Addi	itional Design Requirement	nts: (Sketch)

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